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LMV7235, LMV7239 SNOS5320 – SEPTEMBER 2000 – REVISED APRIL 2018

# LMV7235 and LMV7239 75-ns, Ultra Low Power, Low Voltage, Rail-to-Rail Input Comparator With Open-Drain and Push-Pull Output

## 1 Features

- V<sub>S</sub> = 5 V, T<sub>A</sub> = 25°C (Typical Values Unless Otherwise Specified)
- Propagation Delay: 75 ns
- Low supply Current: 65 μA
- Rail-to-Rail Input
- Open Drain and Push-Pull Output
- Ideal for 2.7-V and 5-V, Single-Supply Applications
- Available in Space-Saving Packages:
  - 5-Pin SOT-23
  - 5-Pin SC70

## 2 Applications

- Portable and Battery-Powered Systems
- Set Top Boxes
- High-Speed Differential Line Receiver
- Window Comparators
- Zero-Crossing Detectors
- High-Speed Sampling Circuits

## 3 Description

The LMV7235 and LMV7239 are ultra low power, low voltage, 75-ns comparators. They are ensured to operate over the full supply voltage range of 2.7 V to 5.5 V. These devices achieve a 75-ns propagation delay while consuming only 65  $\mu$ A of supply current at 5 V.

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The LMV7235 and LMV7239 have a greater than railto-rail common-mode voltage range. The input common mode voltage range extends 200 mV below ground and 200 mV above supply, allowing both ground and supply sensing.

The LMV7235 features an open drain output. By connecting an external resistor, the output of the comparator can be used as a level shifter.

The LMV7239 features a push-pull output stage. This feature allows operation without the need of an external pullup resistor.

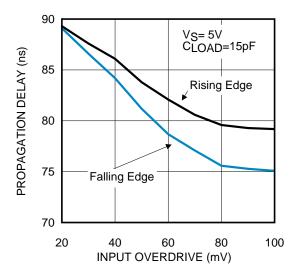
The LMV7235 and LMV7239 are available in the 5pin SC70 and 5-pin SOT-23 packages, which are ideal for systems where small size and low power is critical.

### Device Information<sup>(1)</sup>

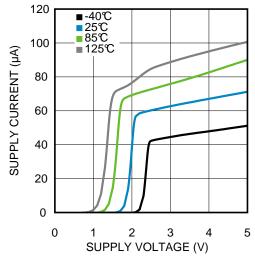
PART NUMBER	PACKAGES	BODY SIZE (NOM)		
	SOT-23 (5)	2.90 mm × 1.60 mm		
LMV7235, LMV7239	SC70 (5)	2.00 mm × 1.25 mm		

(1) For all available packages, see the orderable addendum at the end of the data sheet.

### Propagation Delay vs. Overdrive



# Supply Current vs. Supply Voltage





An IMPORTANT NOTICE at the end of this data sheet addresses availability, warranty, changes, use in safety-critical applications, intellectual property matters and other important disclaimers. PRODUCTION DATA.

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## **4** Revision History

2

NOTE: Page numbers for previous revisions may differ from page numbers in the current version.

C	hanges from Revision N (April 2015) to Revision O	Page
•	Moved the LMV7239-Q1 automotive device to a standalone data sheet (SNOSD85)	1
•	Added minimum values for the input offset voltage in the Electrical Characteristics, 2.7 V table	5
•	Changed the input offset voltage typical value at room temperature from 0.8 to ±0.8 in the <i>Electrical Characteristics</i> , 2.7 V table	
•	Added minimum values for the input offset voltage in the Electrical Characteristics, 5 V table	6
•	Changed the input offset voltage typical value at room temperature from 1 to ±1 in the Electrical Characteristics, 5 V table	

#### Changes from Revision M (February 2013) to Revision N

Added, updated, or renamed the following sections: Device Information Table, Pin Configuration and Functions; Specifications. Detailed DescriptionLayout, Device and Documentation Support, Mechanical, Packaging, and 

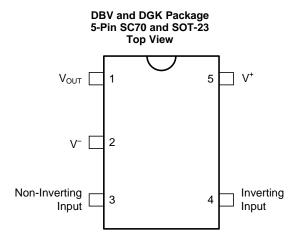
C	hanges from Revision L (February 2013) to Revision M	Page
•	Changed layout of National Data Sheet to TI format	1



## Page



## 5 Pin Configuration and Functions



#### **Pin Functions**

PIN		I/O	DESCRIPTION			
NO.	NAME	1/0	DESCRIPTION			
1	V <sub>OUT</sub>	0	Output			
2	V-	Р	Negative Supply			
3	IN+	I	Noninverting Input			
4	IN-	I	Inverting Input			
5	V+	Р	Positive Supply			



## 6 Specifications

## 6.1 Absolute Maximum Ratings

Over operating free-air temperature range (unless otherwise noted)<sup>(1)</sup>

	MIN	МАХ	UNIT
Differential Input Voltage		± Supply Voltage	V
Output Short Circuit Duration		See <sup>(2)</sup>	
Supply Voltage (V <sup>+</sup> - V <sup>-</sup> )		6	V
SOLDERING INFORMATION		·	
Infrared or Convection (20 sec)		235	°C
Wave Soldering (10 sec)		260 (lead temp)	°C
Voltage at Input/Output Pins		(V <sup>+</sup> ) +0.3, (V <sup>−</sup> ) −0.3	V
Current at Input Pin <sup>(3)</sup>		±10	mA
Storage Temperature, T <sub>stg</sub>	-65	150	°C
Junction Temperature,TJ		150	°C

(1) Stresses beyond those listed under absolute maximum ratings may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under recommended operating conditions is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

(2) Applies to both single-supply and split-supply operation. Continuous short circuit operation at elevated ambient temperature can result in exceeding the maximum allowed junction temperature of 150°C. Output currents in excess of ±30mA over long term may adversely affect reliability.

(3) Limiting input pin current is only necessary for input voltages that exceed absolute maximum input voltage ratings.

## 6.2 ESD Ratings

			VALUE	UNIT
V	Electrostatio discharge	Human-body model (HBM), per ANSI/ESDA/JEDEC JS-001 <sup>(1)</sup>	±1000	V
V <sub>(ESD)</sub>	Electrostatic discharge	Machine model (MM)	±100	v

(1) JEDEC document JEP155 states that 500-V HBM allows safe manufacturing with a standard ESD control process. Manufacturing with less than 500-V HBM is possible with the necessary precautions.

## 6.3 Recommended Operating Conditions

	MIN	MAX	UNIT
Supply Voltages (V <sup>+</sup> - V <sup>-</sup> )	2.7	5.5	V
Temperature Range <sup>(1)</sup>	-40	85	°C

(1) The maximum power dissipation is a function of  $T_{J(MAX)}$ ,  $\theta_{JA}$ . The maximum allowable power dissipation at any ambient temperature is  $P_D = (T_{J(MAX)} - T_A) / \theta_{JA}$ . All numbers apply for packages soldered directly onto a PCB.

#### 6.4 Thermal Information

		LMV7235, L	MV7239	
TF	IERMAL METRIC <sup>(1)</sup>	DGK (SC70)	DBV (SOT-23)	UNIT
		5 PINS	5 PINS	
R <sub>0JA</sub> Junction-to-ambi	ent thermal resistance	478	265	°C/W

(1) For more information about traditional and new thermal metrics, see the Semiconductor and IC Package Thermal Metrics application report.



#### 6.5 Electrical Characteristics, 2.7 V

Unless otherwise specified, all limits ensured for  $T_A = 25^{\circ}C$ ,  $V_{CM} = V^+/2$ ,  $V^+ = 2.7 \text{ V}$ ,  $V^- = 0 \text{ V}^-$ .

	PARAMETER	TEST CO	NDITIONS	MIN <sup>(1)</sup>	TYP <sup>(2)</sup>	MAX <sup>(1)</sup>	UNIT	
				-6	±0.8	+6	mV	
V <sub>OS</sub>	Input Offset Voltage	At temp extremes		-8		+8		
	Insuit Dies Courset				30	400	^	
I <sub>B</sub>	Input Bias Current	At temp extremes				600	nA	
	Input Offset Current				5	200	nA	
l <sub>os</sub>	input Onset Current	At temp extremes				400	ΠA	
CMRR	Common-Mode Rejection Ratio	$0 \text{ V} < \text{V}_{\text{CM}} < 2.7 \text{ V}^{(3)}$		52	62		dB	
PSRR	Power Supply Rejection Ratio	V <sup>+</sup> = 2.7 V to 5 V		65	85		dB	
V <sub>CM</sub>	Input Common-Mode Voltage Range	CMRR > 50 dB	At temp extremes	V <sup>-</sup> -0.1	-0.2 to 2.9	V <sup>+</sup> +0.1	V	
	Output Swing High	I <sub>L</sub> = 4 mA, V <sub>ID</sub> = 500 mV		V <sup>+</sup> -0.35	V <sup>+</sup> -0.26		V	
Vo	(LMV7239 only)	$\begin{split} I_L &= 0.4 \text{ mA}, \\ V_{\text{ID}} &= 500 \text{ mV} \end{split}$			V <sup>+</sup> -0.02		V	
	Output Swing Low	$I_{L} = -4 \text{ mA},$ $V_{ID} = -500 \text{ mV}$			230	350	mV	
		At temp extremes				450		
		I <sub>L</sub> = −0.4 mA, V <sub>ID</sub> = −500 mV			15		mV	
		Sourcing, $V_0 = 0 V$ (LMV7239 only)			15		mA	
I <sub>SC</sub>	Output Short Circuit Current	Sinking, V <sub>O</sub> = 2.7 V (LMV7235, R <sub>L</sub> = 10 k)			20		mA	
	Current Current	No load			52	85		
I <sub>S</sub>	Supply Current	At temp extremes				100	μA	
		$\begin{array}{l} \text{Overdrive} = 20 \text{ mV} \\ \text{C}_{\text{LOAD}} = 15 \text{ pF}^{(4)} \end{array}$			96		ns	
t <sub>PD</sub>	Propagation Delay	$\begin{array}{l} \text{Overdrive} = 50 \text{ mV} \\ \text{C}_{\text{LOAD}} = 15 \text{ pF}^{(4)} \end{array}$			87		ns	
		$\begin{array}{l} \text{Overdrive} = 100 \text{ mV} \\ \text{C}_{\text{LOAD}} = 15 \text{ pF}^{(4)} \end{array}$			85		ns	
t <sub>skew</sub>	Propagation Delay Skew (LMV7239 only)	Overdrive = 20 mV <sup>(5)</sup>			2		ns	
	Output Disc Time	LMV7239/LMV7239Q 10% to 90%			1.7		ns	
t <sub>r</sub>	Output Rise Time	LMV7235 10% to 90% <sup>(4)</sup>			112		ns	
t <sub>f</sub>	Output Fall Time	90% to 10%			1.7		ns	
I <sub>LEAKAGE</sub>	Output Leakage Current (LMV7235 only)				3		nA	

(1) All limits are ensured by testing or statistical analysis.

(2) Typical values represent the most likely parametric norm as determined at the time of characterization. Actual typical values may vary over time and will also depend on the application and configuration. The typical values are not tested and are not guaranteed on shipped production material.

(3) CMRR is not linear over the common mode range. Limits are guaranteed over the worst case from 0 to V<sub>CC/2</sub> or V<sub>CC/2</sub> to V<sub>CC</sub>.

(4) A 10k pullup resistor was used when measuring the LMV7235. The rise time of the LMV7235 is a function of the R-C time constant.
 (5) Propagation Delay Skew is defined as the absolute value of the difference between t<sub>PDLH</sub> and t<sub>PDHL</sub>.

#### LMV7235, LMV7239

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## 6.6 Electrical Characteristics, 5 V

Unless otherwise specified, all limits ensured for  $T_A = 25^{\circ}$ C,  $V_{CM} = V^+/2$ ,  $V^+ = 5$  V,  $V^- = 0$  V.

	PARAMETER	TEST CO	NDITIONS	MIN <sup>(1)</sup>	TYP <sup>(2)</sup>	MAX <sup>(1)</sup>	UNIT	
	lanut Offert \/eltere			-6	±1	+6		
V <sub>OS</sub>	Input Offset Voltage	At temp extremes		-8		+8	mV	
	lanut Dian Ourrent				30	400	nA	
I <sub>B</sub>	Input Bias Current	At temp extremes				600	ΠA	
los	Input Offset Current				5	200	nA	
105		At temp extremes				400	10.4	
CMRR	Common-Mode Rejection Ratio	0 V < V <sub>CM</sub> < 5 V		52	67		dB	
PSRR	Power Supply Rejection Ratio	$V^{+} = 2.7 V \text{ to } 5 V$		65	85		dB	
V <sub>CM</sub>	Input Common-Mode Voltage Range	CMRR > 50dB		V <sup>−</sup> −0.1	−0.2 to 5.2	V <sup>+</sup> +0.1	V	
	Range		At temp extremes	V <sup>-</sup>		V <sup>+</sup>		
	Output Swing High	$I_L = 4 \text{ mA},$ $V_{ID} = 500 \text{ mV}$		V <sup>+</sup> -0.25	V <sup>+</sup> −0.15		V	
Vo	(LMV7239 only)	$\begin{split} I_L &= 0.4 \text{ mA}, \\ V_{\text{ID}} &= 500 \text{ mV} \end{split}$			V <sup>+</sup> -0.01		V	
	Output Swing Low	I <sub>L</sub> = −4 mA, V <sub>ID</sub> = −500 mV			230	350	mV	
			At temp extremes			450		
		I <sub>L</sub> = −0.4 mA, V <sub>ID</sub> = −500 mV			10		mV	
		Sourcing, $V_0 = 0 V$ (LMV7239 only) Sinking, $V_0 = 5 V$		25	55		mA	
I <sub>SC</sub>	Output Short Circuit Current		At temp extremes	15				
ISC	ouput onon onour ouron			30	60		mA	
		(LMV7235, R <sub>L</sub> = 10k)	At temp extremes	20				
Is	Supply Current	No load			65	95	μA	
•			At temp extremes			110		
		$\begin{array}{l} \text{Overdrive} = 20 \text{ mV} \\ \text{C}_{\text{LOAD}} = 15 \text{ pF}^{(3)} \end{array}$			89		ns	
t <sub>PD</sub>	Propagation Delay	$\begin{array}{l} \text{Overdrive} = 50 \text{ mV} \\ \text{C}_{\text{LOAD}} = 15 \text{ pF}^{(3)} \end{array}$			82		ns	
		$\begin{array}{l} \text{Overdrive} = 100 \text{ mV} \\ \text{C}_{\text{LOAD}} = 15 \text{ pF}^{(3)} \end{array}$			75		ns	
t <sub>SKEW</sub>	Propagation Delay Skew (LMV7239 only)	Overdrive = $20 \text{ mV}^{(4)}$			1		ns	
		LMV7239 10% to 90%			1.2		ns	
t <sub>r</sub>	Output Rise Time	LMV7235 10% to 90%			100		ns	
t <sub>f</sub>	Output Fall Time	90% to 10%			1.2		ns	
I <sub>LEAKAGE</sub>	Output Leakage Current (LMV7235 only)				3		nA	

 All limits are ensured by testing or statistical analysis.
 Typical values represent the most likely parametric norm as determined at the time of characterization. Actual typical values may vary over time and will also depend on the application and configuration. The typical values are not tested and are not guaranteed on shipped production material.

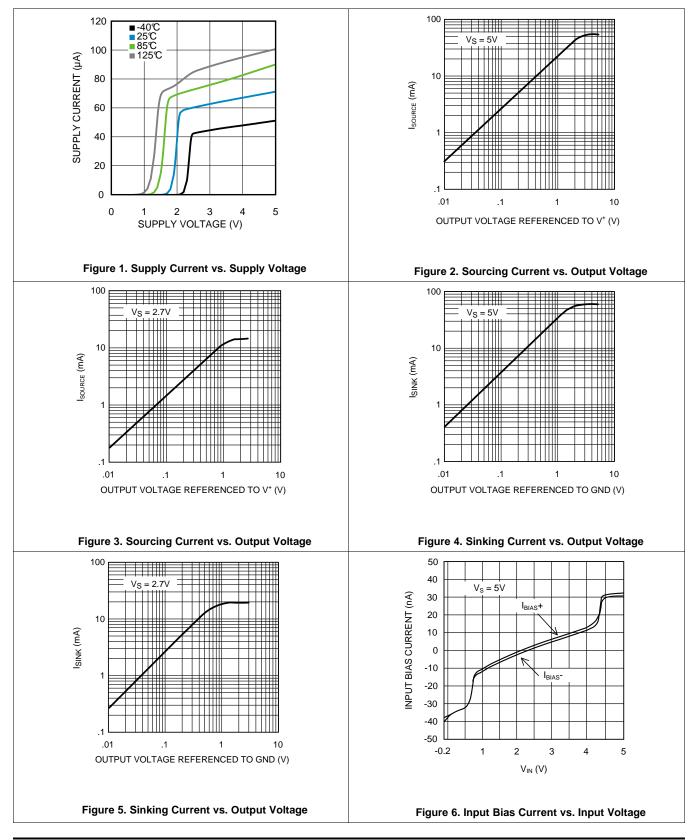
A 10k pullup resistor was used when measuring the LMV7235. The rise time of the LMV7235 is a function of the R-C time constant. (3)

(4) Propagation Delay Skew is defined as the absolute value of the difference between tPDLH and tPDHL.



## 6.7 Typical Characteristics

(Unless otherwise specified,  $V_S$  = 5V,  $C_L$  = 10pF,  $T_A$  = 25°C).



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### LMV7235, LMV7239

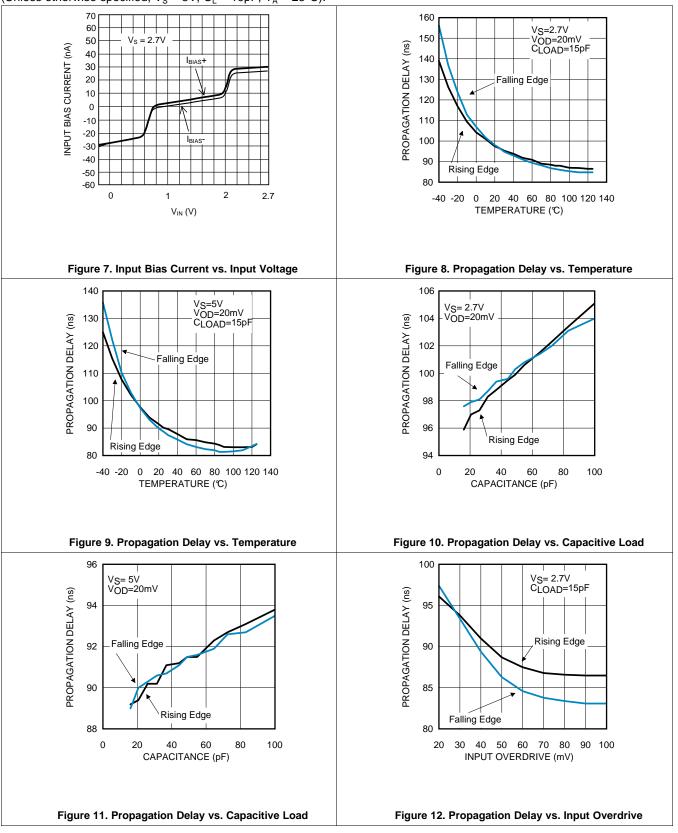
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## **Typical Characteristics (continued)**

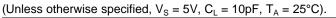
(Unless otherwise specified,  $V_S = 5V$ ,  $C_L = 10pF$ ,  $T_A = 25^{\circ}C$ ).

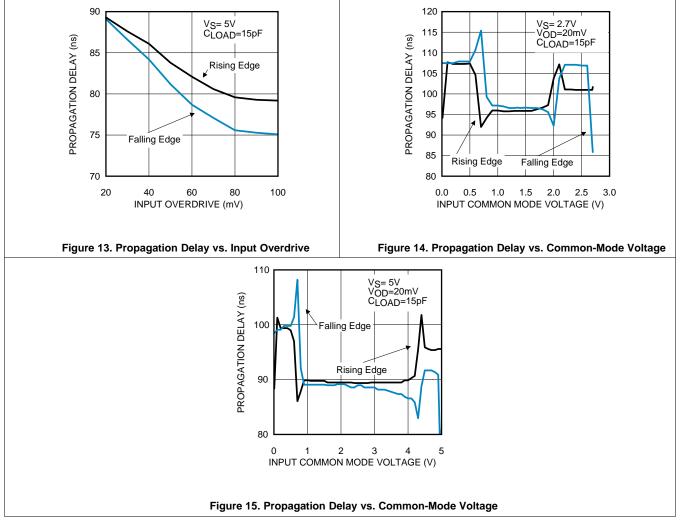


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### **Typical Characteristics (continued)**





## 7 Detailed Description

### 7.1 Overview

The LMV7235 and LMV7239 are ultra low power, low voltage, 75-ns comparators. They are ensured to operate over the full supply voltage range of 2.7 V to 5.5 V. These devices achieve a 75-ns propagation delay while consuming only 65  $\mu$ A of supply current at 5 V.

The LMV7235 and LMV7239 have a greater than rail-to-rail common-mode voltage range. The input common-mode voltage range extends 200 mV below ground and 200 mV above supply, allowing both ground and supply sensing.

### 7.2 Functional Block Diagram

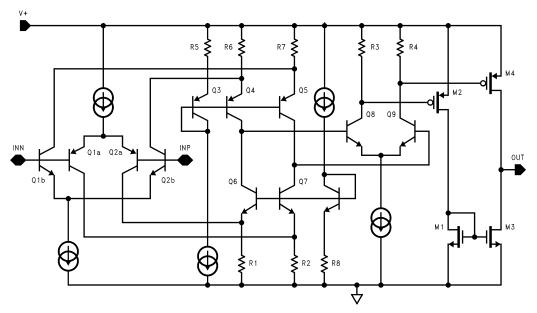


Figure 16. Simplified Schematic of LMV7239

### 7.3 Feature Description

### 7.3.1 Input Stage

The LMV7235 and LMV7239 are rail-to-rail input and output. The typical input common-mode voltage range of -0.2 V below the ground to 0.2 V above the supply. The LMV7235 and LMV7239 use a complimentary PNP and NPN input stage in which the PNP stage senses common-mode voltage near V<sup>-</sup> and the NPN stage senses common-mode voltage near V<sup>+</sup>. If either of the input signals falls below the negative common mode limit, the parasitic PN junction formed by the substrate and the base of the PNP will turn on resulting in an increase of input bias current.

If one of the inputs goes above the positive common mode limit, the output will still maintain the correct logic level as long as the other input stays within the common mode range. However, the propagation delay will increase. When both inputs are outside the common-mode voltage range, current saturation occurs in the input stage, and the output becomes unpredictable.

The propagation delay does not increase significantly with large differential input voltages. However, large differential voltages greater than the supply voltage should be avoided to prevent damage to the input stage.

#### 7.3.2 Output Stage: LMV7239

The LMV7239 has a push-pull output. When the output switches, there is a low resistance path between  $V_{CC}$  and ground, causing high output sinking or sourcing current during the transition.



## Feature Description (continued)

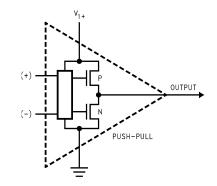


Figure 17. LMV7239 Push-Pull Output Stage

#### 7.3.3 Output Stage: LMV7235

The LMV7235 has an open drain that requires a pull-up resistor to a positive supply voltage for the output to switch properly. The internal circuitry is identical to the LMV7239 except that the upper P channel output device M4 is absent in the Functional Block Diagram above. When the internal output transistor is off, the output voltage will be pulled up to the external positive voltage by the external pull-up resistor. This allows the output to be OR'ed with other open drain outputs on the same bus. The output pull-up resistor can be connected to any voltage level between V- and V+ for level shifting applications.

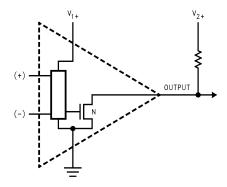


Figure 18. LMV7235 Open Drain Output

### 7.4 Device Functional Modes

#### 7.4.1 Capacitive and Resistive Loads

The propagation delay on the rising edge of the LMV7235 depends on the load resistance and capacitance values.

#### 7.4.2 Noise

Most comparators have rather low gain. This allows the output to spend time between high and low when the input signal changes slowly. The result is the output may oscillate between high and low when the differential input is near zero. The high gain of this comparator eliminates this problem. Less than 1  $\mu$ V of change on the input will drive the output from one rail to the other rail. If the input signal is noisy, the output cannot ignore the noise unless some hysteresis is provided by positive feedback. (See *Hysteresis*.)

#### 7.4.3 Hysteresis

To improve propagation delay when low overdrive is needed hysteresis can be added.

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### **Device Functional Modes (continued)**

#### 7.4.3.1 Inverting Comparator With Hysteresis

The inverting comparator with hysteresis requires a three resistor network that is referenced to the supply voltage V<sup>+</sup> of the comparator as shown in Figure 19. When V<sub>IN</sub> at the inverting input is less than V<sub>A</sub>, the voltage at the noninverting node of the comparator (V<sub>IN</sub> < V<sub>A</sub>), the output voltage is high (for simplicity assume V<sub>O</sub> switches as high as V<sup>+</sup>). The three network resistors can be represented as R<sub>1</sub>//R<sub>3</sub> in series with R<sub>2</sub>.

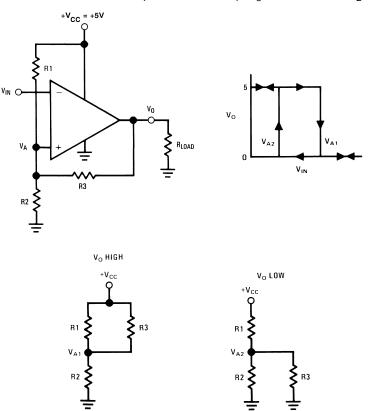


Figure 19. Inverting Comparator With Hysteresis

The lower input trip voltage V<sub>A1</sub> is defined as:

$$V_{A1} = V_{CC}R_2 / [(R_1 // R_3) + R_2)]$$
(1)

When  $V_{IN}$  is greater than  $V_A$ , the output voltage is low or very close to ground. In this case the three network resistors can be presented as  $R_2 //R_3$  in series with  $R_1$ .

The upper trip voltage V<sub>A2</sub> is defined as:

$$V_{A2} = V_{CC} (R_2 // R_3) / [(R_1) + (R_2 // R_3)]$$

The total hysteresis provided by the network is defined as  $\Delta V_A = V_{A1} - V_{A2}$ .

$$\Delta V_{A} = \frac{+V_{CC}R_{1}R_{2}}{R_{1}R_{2} + R_{1}R_{3} + R_{2}R_{3}}$$
(3)

#### 7.4.3.2 Non-Inverting Comparator With Hysteresis

A noninverting comparator with hysteresis requires a two resistor network, and a voltage reference ( $V_{REF}$ ) at the inverting input. When  $V_{IN}$  is low, the output is also low. For the output to switch from low to high,  $V_{IN}$  must rise up to  $V_{IN1}$  where  $V_{IN1}$  is calculated by:

$$\Delta V_{\rm IN1} = \frac{V_{\rm REF}(R_1 + R_2)}{R_2}$$

As soon as  $V_O$  switches to  $V_{CC}$ ,  $V_A$  steps to a value greater than  $V_{REF}$  which is given by:

(4)

(2)



(7)

#### **Device Functional Modes (continued)**

$$V_{A} = V_{IN} + \frac{(V_{CC} - V_{IN1})R_{1}}{R_{1} + R_{2}}$$
(5)

To make the comparator switch back to its low state,  $V_{IN}$  must equal  $V_{REF}$  before  $V_A$  will again equal  $V_{REF}$ .  $V_{IN2}$  can be calculated by:

$$V_{\rm IN2} = \frac{V_{\rm REF}(R_1 + R_2) - V_{\rm CC}R_1}{R_2}$$
(6)

The hysteresis of this circuit is the difference between  $V_{IN1}$  and  $V_{IN2}$ .

 $\Delta V_{IN} = V_{CC}R_1 / R_2$ 

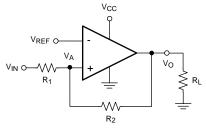


Figure 20. Noninverting Comparator With Hysteresis

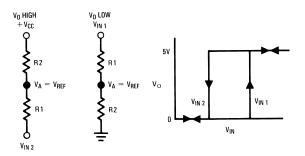


Figure 21. Noninverting Comparator Thresholds

#### 7.4.4 Zero Crossing Detector

In a zero crossing detector circuit, the inverting input is connected to ground and the noninverting input is connected to a 100 mV<sub>PP</sub> AC signal. As the signal at the noninverting input crosses 0V, the comparator's output changes state.

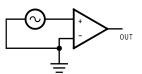


Figure 22. Simple Zero Crossing Detector

#### 7.4.4.1 Zero Crossing Detector With Hysteresis

To improve switching times and centering the input threshold to ground a small amount of positive feedback is added to the circuit. Voltage divider  $R_4$  and  $R_5$  establishes a reference voltage,  $V_1$ , at the positive input. By making the series resistance,  $R_1$  plus  $R_2$  equal to  $R_5$ , the switching condition,  $V_1 = V_2$ , will be satisfied when  $V_{IN} = 0$ .

The positive feedback resistor,  $R_6$ , is made very large with respect to  $R_5 \parallel R_6 = 2000 R_5$ ). The resultant hysteresis established by this network is very small ( $\Delta V_1 < 10 \text{ mV}$ ) but it is sufficient to insure rapid output voltage transitions.

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#### LMV7235, LMV7239 SNOS5320 – SEPTEMBER 2000 – REVISED APRIL 2018



### **Device Functional Modes (continued)**

Diode  $D_1$  is used to ensure that the inverting input terminal of the comparator never goes below approximately -100 mV. As the input terminal goes negative,  $D_1$  will forward bias, clamping the node between  $R_1$  and  $R_2$  to approximately -700 mV. This sets up a voltage divider with  $R_2$  and  $R_3$  preventing  $V_2$  from going below ground. The maximum negative input overdrive is limited by the current handling ability of  $D_1$ .

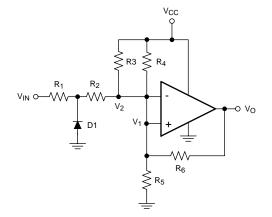


Figure 23. Zero Crossing Detector With Hysteresis

#### 7.4.5 Threshold Detector

Instead of tying the inverting input to 0 V, the inverting input can be tied to a reference voltage. As the input on the noninverting input passes the  $V_{REF}$  threshold, the comparator's output changes state. It is important to use a stable reference voltage to ensure a consistent switching point.

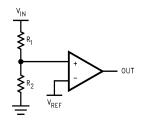


Figure 24. Threshold Detector



## 8 Application and Implementation

#### NOTE

Information in the following applications sections is not part of the TI component specification, and TI does not warrant its accuracy or completeness. TI's customers are responsible for determining suitability of components for their purposes. Customers should validate and test their design implementation to confirm system functionality.

#### 8.1 Application Information

The LMV7235 and LMV7239 are single supply comparators with 75 ns of propagation delay and only 65  $\mu$ A of supply current.

#### 8.2 Typical Applications

#### 8.2.1 Square Wave Oscillator

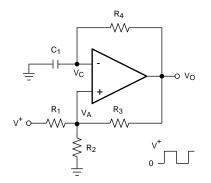


Figure 25. Square Wave Oscillator

#### 8.2.1.1 Design Requirements

A typical application for a comparator is as a square wave oscillator. The circuit in Figure 25 generates a square wave whose period is set by the RC time constant of the capacitor  $C_1$  and resistor  $R_4$ .

#### 8.2.1.2 Detailed Design Procedure

The maximum frequency is limited by the large signal propagation delay of the comparator and by the capacitive loading at the output, which limits the output slew rate.

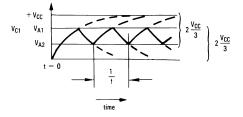


Figure 26. Square Wave Oscillator Timing Thresholds

Consider the output of Figure 25 to be high to analyze the circuit. That implies that the inverted input ( $V_c$ ) is lower than the noninverting input ( $V_A$ ). This causes the C<sub>1</sub> to be charged through R<sub>4</sub>, and the voltage V<sub>C</sub> increases until it is equal to the noninverting input. The value of V<sub>A</sub> at this point is:

$$V_{A1} = \frac{V_{CC} \cdot R_2}{R_2 + R_1 \parallel R_3}$$

If  $R_1 = R_2 = R_3$ , then V <sub>A1</sub> = 2 V<sub>cc</sub>/3

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## Typical Applications (continued)

At this point the comparator switches pulling down the output to the negative rail. The value of V<sub>A</sub> at this point is:

$$V_{A2} = \frac{V_{CC}(R_2 || R_3)}{R_1 + (R_2 || R_3)}$$
(9)

If  $R_1 = R_2 = R_3$ , then  $V_{A2} = V_{CC}/3$ .

The capacitor C1 now discharges through R4, and the voltage VC decreases until it is equal to VA2, at which point the comparator switches again, bringing it back to the initial stage. The time period is equal to twice the time it takes to discharge C<sub>1</sub> from  $2V_{CC}/3$  to  $V_{CC}/3$ , which is given by R<sub>4</sub>C<sub>1</sub>·In2. Hence the formula for the frequency is:

$$F = 1/(2 \cdot R_4 \cdot C_4 \cdot \ln 2)$$

The LMV7239 should be used for a symmetrical output. The LMV7235 will require a pullup resistor on the output to function, and will have a slightly asymmetrical output due to the reduced sourcing current.

#### 8.2.1.3 Application Curves

Figure 27 shows the simulated results of an oscillator using the following values:

- 1.  $R_1 = R_2 = R_3 = R_4 = 100 \text{ k}\Omega$
- 2.  $C_1 = 100 \text{ pF}, C_1 = 20 \text{ pF}$
- 3. V+ = 5 V, V- = GND
- 4.  $C_{STRAY}$  (not shown) from Va to GND = 10 pF

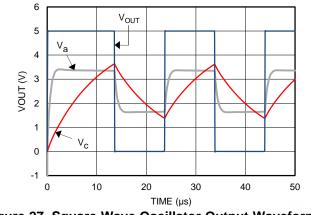


Figure 27. Square Wave Oscillator Output Waveform

#### 8.2.2 Crystal Oscillator

A simple crystal oscillator using the LMV7235 or LMV7239 is shown in Figure 28. Resistors R<sub>1</sub> and R<sub>2</sub> set the bias point at the comparator's noninverting input. Resistors, R<sub>3</sub> and R<sub>4</sub> and capacitor C<sub>1</sub> set the inverting input node at an appropriate DC average level based on the output. The crystal's path provides resonant positive feedback and stable oscillation occurs. The output duty cycle for this circuit is roughly 50%, but it is affected by resistor tolerances and to a lesser extent by the comparator

(10)



## **Typical Applications (continued)**

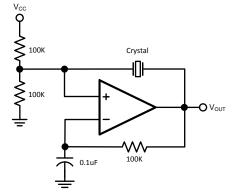
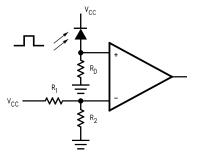


Figure 28. Crystal Oscillator

#### 8.2.3 Infrared (IR) Receiver

The LMV7235 and LMV7239 can also be used as an infrared receiver. The infrared photo diode creates a current relative to the amount of infrared light present. The current creates a voltage across RD. When this voltage level cross the voltage applied by the voltage divider to the inverting input, the output transitions.





### 8.2.4 Window Detector

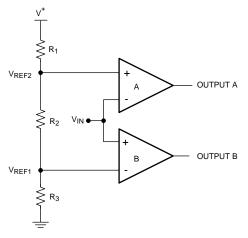


Figure 30. Window Detector

A window detector monitors the input signal to determine if it falls between two voltage levels. Both outputs are true (high) when  $V_{REF1} < V_{IN} < V_{REF2}$ 



## Typical Applications (continued)

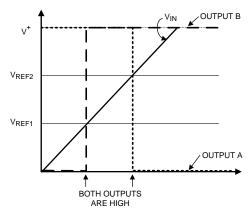


Figure 31. Window Detector Output Signal

The comparator outputs A and B are high only when  $V_{REF1} < V_{IN} < V_{REF2}$ , or "within the window", where these are defined as:

$$V_{REF1} = R_3/R_1 + R_2 + R_3) \times V +$$

$$V_{REF2} = R_2 + R_3/R_1 + R_2 + R_3) \times V +$$
(11)
(12)

To determine if the input signal falls outside of the two voltage levels, both inputs on each comparators can be reversed to invert the logic.

The LMV7235 with an open drain output should be used if the outputs are to be tied together for a common logic output.

Other names for window detectors are: threshold detector, level detector, and amplitude trigger or detector.

## 9 Power Supply Recommendations

To minimize supply noise, power supplies should be decoupled by a  $0.01-\mu$ F ceramic capacitor in parallel with a  $10-\mu$ F capacitor.

Due to the nanosecond edges on the output transition, peak supply currents will be drawn during the time the output is transitioning. Peak current depends on the capacitive loading on the output. The output transition can cause transients on poorly bypassed power supplies. These transients can cause a poorly bypassed power supply to "ring" due to trace inductance and low self-resonance frequency of high ESR bypass capacitors.

Treat the LMV7235 and LMV72391 as high-speed devices. Keep the ground paths short and place small (low ESR ceramic) bypass capacitors directly between the V+ and V- pins.

Output capacitive loading and output toggle rate will cause the average supply current to rise over the quiescent current.



## 10 Layout

### **10.1 Layout Guidelines**

Proper grounding and the use of a ground plane will help to ensure the specified performance of the LMV7235 and LMV72391. Minimizing trace lengths, reducing unwanted parasitic capacitance and using surface-mount components will also help. Comparators are very sensitive to input noise.

The LMV7235 and LMV72391 require a high-speed layout. Follow these layout guidelines:

- 1. Use printed-circuit board with a good, unbroken low-inductance ground plane.
- 2. Place a decoupling capacitor (0.1-µF, ceramic surface-mount capacitor) as close as possible to V<sub>CC</sub> pin.
- 3. On the inputs and the output, keep lead lengths as short as possible to avoid unwanted parasitic feedback around the comparator. Keep inputs away from output.
- 4. Solder the device directly to the printed-circuit board rather than using a socket.
- For slow moving input signals, take care to prevent parasitic feedback. A small capacitor (1000 pF or less) placed between the inputs can help eliminate oscillations in the transition region. This capacitor causes some degradation to t<sub>PD</sub> when the source impedance is low.
- 6. The top-side ground plane runs between the output and inputs.
- 7. Ground trace from the ground pin runs under the device up to the bypass capacitor, shielding the inputs from the outputs.

## 10.2 Layout Example

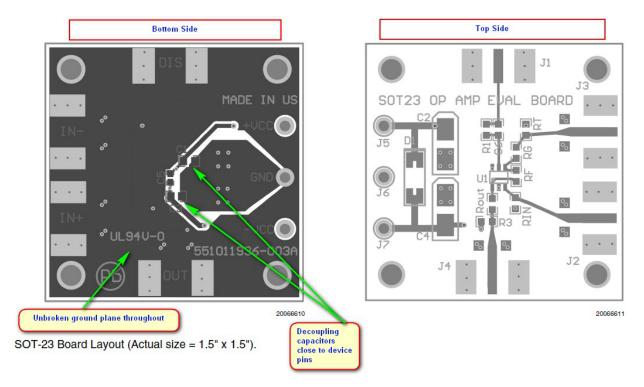


Figure 32. SOT-23 Board Layout Example

TEXAS INSTRUMENTS

www.ti.com

## **11** Device and Documentation Support

#### 11.1 Device Support

#### 11.1.1 Development Support

LMV7239 TINA SPICE Model, SNOM392

TINA-TI SPICE-Based Analog Simulation Program, http://www.ti.com/tool/tina-ti

DIP Adapter Evaluation Module, http://www.ti.com/tool/dip-adapter-evm

TI Universal Operational Amplifier Evaluation Module, http://www.ti.com/tool/opampevm

#### **11.2 Documentation Support**

#### 11.2.1 Related Documentation

A Quad of Independently Func Comparators (SNOA654)

### 11.3 Related Links

The table below lists quick access links. Categories include technical documents, support and community resources, tools and software, and quick access to sample or buy.

PARTS	PRODUCT FOLDER	SAMPLE & BUY	TECHNICAL DOCUMENTS	TOOLS & SOFTWARE	SUPPORT & COMMUNITY
LMV7235	Click here	Click here	Click here	Click here	Click here
LMV7239	Click here	Click here	Click here	Click here	Click here

#### Table 1. Related Links

### 11.4 Receiving Notification of Documentation Updates

To receive notification of documentation updates, navigate to the device product folder on ti.com. In the upper right corner, click on *Alert me* to register and receive a weekly digest of any product information that has changed. For change details, review the revision history included in any revised document.

### 11.5 Community Resources

The following links connect to TI community resources. Linked contents are provided "AS IS" by the respective contributors. They do not constitute TI specifications and do not necessarily reflect TI's views; see TI's Terms of Use.

TI E2E<sup>™</sup> Online Community *TI's Engineer-to-Engineer (E2E) Community.* Created to foster collaboration among engineers. At e2e.ti.com, you can ask questions, share knowledge, explore ideas and help solve problems with fellow engineers.

**Design Support TI's Design Support** Quickly find helpful E2E forums along with design support tools and contact information for technical support.

## 11.6 Trademarks

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#### **11.7 Electrostatic Discharge Caution**



This integrated circuit can be damaged by ESD. Texas Instruments recommends that all integrated circuits be handled with appropriate precautions. Failure to observe proper handling and installation procedures can cause damage.

ESD damage can range from subtle performance degradation to complete device failure. Precision integrated circuits may be more susceptible to damage because very small parametric changes could cause the device not to meet its published specifications.



### 11.8 Glossary

## SLYZ022 — TI Glossary.

This glossary lists and explains terms, acronyms, and definitions.

## 12 Mechanical, Packaging, and Orderable Information

The following pages include mechanical, packaging, and orderable information. This information is the most current data available for the designated devices. This data is subject to change without notice and revision of this document. For browser-based versions of this data sheet, refer to the left-hand navigation.



## PACKAGING INFORMATION

Orderable part number	Status (1)	Material type	Package   Pins	Package qty   Carrier	<b>RoHS</b> (3)	Lead finish/ Ball material	MSL rating/ Peak reflow	Op temp (°C)	Part marking
	(1)	(2)			(3)	(4)	(5)		(0)
LMV7235M5	Obsolete	Production	SOT-23 (DBV)   5	-	-	Call TI	Call TI	-40 to 85	C21A
LMV7235M5/NOPB	Active	Production	SOT-23 (DBV)   5	1000   SMALL T&R	Yes	SN	Level-1-260C-UNLIM	-40 to 85	C21A
LMV7235M5/NOPB.A	Active	Production	SOT-23 (DBV)   5	1000   SMALL T&R	Yes	SN	Level-1-260C-UNLIM	-40 to 85	C21A
LMV7235M5X	Obsolete	Production	SOT-23 (DBV)   5		-	Call TI	Call TI	-40 to 85	C21A
LMV7235M5X/NOPB	Active	Production	SOT-23 (DBV)   5	3000   LARGE T&R	Yes	SN	Level-1-260C-UNLIM	-40 to 85	C21A
LMV7235M5X/NOPB.A	Active	Production	SOT-23 (DBV)   5	3000   LARGE T&R	Yes	SN	Level-1-260C-UNLIM	-40 to 85	C21A
LMV7235M7	Obsolete	Production	SC70 (DCK)   5	-	-	Call TI	Call TI	-40 to 85	C21
LMV7235M7/NOPB	Active	Production	SC70 (DCK)   5	1000   SMALL T&R	Yes	SN	Level-1-260C-UNLIM	-40 to 85	C21
LMV7235M7/NOPB.A	Active	Production	SC70 (DCK)   5	1000   SMALL T&R	Yes	SN	Level-1-260C-UNLIM	-40 to 85	C21
LMV7235M7X/NOPB	Active	Production	SC70 (DCK)   5	3000   LARGE T&R	Yes	SN	Level-1-260C-UNLIM	-40 to 85	C21
LMV7235M7X/NOPB.A	Active	Production	SC70 (DCK)   5	3000   LARGE T&R	Yes	SN	Level-1-260C-UNLIM	-40 to 85	C21
LMV7239M5/NOPB	Active	Production	SOT-23 (DBV)   5	1000   SMALL T&R	Yes	SN	Level-1-260C-UNLIM	-40 to 85	C20A
LMV7239M5/NOPB.A	Active	Production	SOT-23 (DBV)   5	1000   SMALL T&R	Yes	SN	Level-1-260C-UNLIM	-40 to 85	C20A
LMV7239M5X/NOPB	Active	Production	SOT-23 (DBV)   5	3000   LARGE T&R	Yes	SN	Level-1-260C-UNLIM	-40 to 85	C20A
LMV7239M5X/NOPB.A	Active	Production	SOT-23 (DBV)   5	3000   LARGE T&R	Yes	SN	Level-1-260C-UNLIM	-40 to 85	C20A
LMV7239M7/NOPB	Active	Production	SC70 (DCK)   5	1000   SMALL T&R	Yes	SN	Level-1-260C-UNLIM	-40 to 85	C20
LMV7239M7/NOPB.A	Active	Production	SC70 (DCK)   5	1000   SMALL T&R	Yes	SN	Level-1-260C-UNLIM	-40 to 85	C20
LMV7239M7X/NOPB	Active	Production	SC70 (DCK)   5	3000   LARGE T&R	Yes	SN	Level-1-260C-UNLIM	-40 to 85	C20
LMV7239M7X/NOPB.A	Active	Production	SC70 (DCK)   5	3000   LARGE T&R	Yes	SN	Level-1-260C-UNLIM	-40 to 85	C20

<sup>(1)</sup> **Status:** For more details on status, see our product life cycle.

<sup>(2)</sup> Material type: When designated, preproduction parts are prototypes/experimental devices, and are not yet approved or released for full production. Testing and final process, including without limitation quality assurance, reliability performance testing, and/or process qualification, may not yet be complete, and this item is subject to further changes or possible discontinuation. If available for ordering, purchases will be subject to an additional waiver at checkout, and are intended for early internal evaluation purposes only. These items are sold without warranties of any kind.

<sup>(3)</sup> RoHS values: Yes, No, RoHS Exempt. See the TI RoHS Statement for additional information and value definition.

<sup>(4)</sup> Lead finish/Ball material: Parts may have multiple material finish options. Finish options are separated by a vertical ruled line. Lead finish/Ball material values may wrap to two lines if the finish value exceeds the maximum column width.



23-May-2025

<sup>(5)</sup> MSL rating/Peak reflow: The moisture sensitivity level ratings and peak solder (reflow) temperatures. In the event that a part has multiple moisture sensitivity ratings, only the lowest level per JEDEC standards is shown. Refer to the shipping label for the actual reflow temperature that will be used to mount the part to the printed circuit board.

<sup>(6)</sup> Part marking: There may be an additional marking, which relates to the logo, the lot trace code information, or the environmental category of the part.

Multiple part markings will be inside parentheses. Only one part marking contained in parentheses and separated by a "~" will appear on a part. If a line is indented then it is a continuation of the previous line and the two combined represent the entire part marking for that device.

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#### OTHER QUALIFIED VERSIONS OF LMV7239 :

Automotive : LMV7239-Q1

NOTE: Qualified Version Definitions:

• Automotive - Q100 devices qualified for high-reliability automotive applications targeting zero defects



Texas

STRUMENTS

## TAPE AND REEL INFORMATION





#### QUADRANT ASSIGNMENTS FOR PIN 1 ORIENTATION IN TAPE



*All dimensions are nominal												
Device	Package Type	Package Drawing		SPQ	Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
LMV7235M5/NOPB	SOT-23	DBV	5	1000	178.0	8.4	3.2	3.2	1.4	4.0	8.0	Q3
LMV7235M5X/NOPB	SOT-23	DBV	5	3000	178.0	8.4	3.2	3.2	1.4	4.0	8.0	Q3
LMV7235M7/NOPB	SC70	DCK	5	1000	178.0	8.4	2.25	2.45	1.2	4.0	8.0	Q3
LMV7235M7X/NOPB	SC70	DCK	5	3000	178.0	8.4	2.25	2.45	1.2	4.0	8.0	Q3
LMV7239M5/NOPB	SOT-23	DBV	5	1000	178.0	8.4	3.2	3.2	1.4	4.0	8.0	Q3
LMV7239M5X/NOPB	SOT-23	DBV	5	3000	178.0	8.4	3.2	3.2	1.4	4.0	8.0	Q3
LMV7239M7/NOPB	SC70	DCK	5	1000	178.0	8.4	2.25	2.45	1.2	4.0	8.0	Q3
LMV7239M7X/NOPB	SC70	DCK	5	3000	178.0	8.4	2.25	2.45	1.2	4.0	8.0	Q3



# PACKAGE MATERIALS INFORMATION

18-Oct-2024



Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)
LMV7235M5/NOPB	SOT-23	DBV	5	1000	208.0	191.0	35.0
LMV7235M5X/NOPB	SOT-23	DBV	5	3000	208.0	191.0	35.0
LMV7235M7/NOPB	SC70	DCK	5	1000	208.0	191.0	35.0
LMV7235M7X/NOPB	SC70	DCK	5	3000	208.0	191.0	35.0
LMV7239M5/NOPB	SOT-23	DBV	5	1000	208.0	191.0	35.0
LMV7239M5X/NOPB	SOT-23	DBV	5	3000	208.0	191.0	35.0
LMV7239M7/NOPB	SC70	DCK	5	1000	208.0	191.0	35.0
LMV7239M7X/NOPB	SC70	DCK	5	3000	208.0	191.0	35.0

# **DBV0005A**



## **PACKAGE OUTLINE**

## SOT-23 - 1.45 mm max height

SMALL OUTLINE TRANSISTOR



NOTES:

- 1. All linear dimensions are in millimeters. Any dimensions in parenthesis are for reference only. Dimensioning and tolerancing per ASME Y14.5M.
   This drawing is subject to change without notice.
   Reference JEDEC MO-178.

- 4. Body dimensions do not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not exceed 0.25 mm per side.
- 5. Support pin may differ or may not be present.



## DBV0005A

# **EXAMPLE BOARD LAYOUT**

## SOT-23 - 1.45 mm max height

SMALL OUTLINE TRANSISTOR



NOTES: (continued)

6. Publication IPC-7351 may have alternate designs.

7. Solder mask tolerances between and around signal pads can vary based on board fabrication site.



## DBV0005A

# **EXAMPLE STENCIL DESIGN**

## SOT-23 - 1.45 mm max height

SMALL OUTLINE TRANSISTOR



NOTES: (continued)

8. Laser cutting apertures with trapezoidal walls and rounded corners may offer better paste release. IPC-7525 may have alternate design recommendations.

9. Board assembly site may have different recommendations for stencil design.



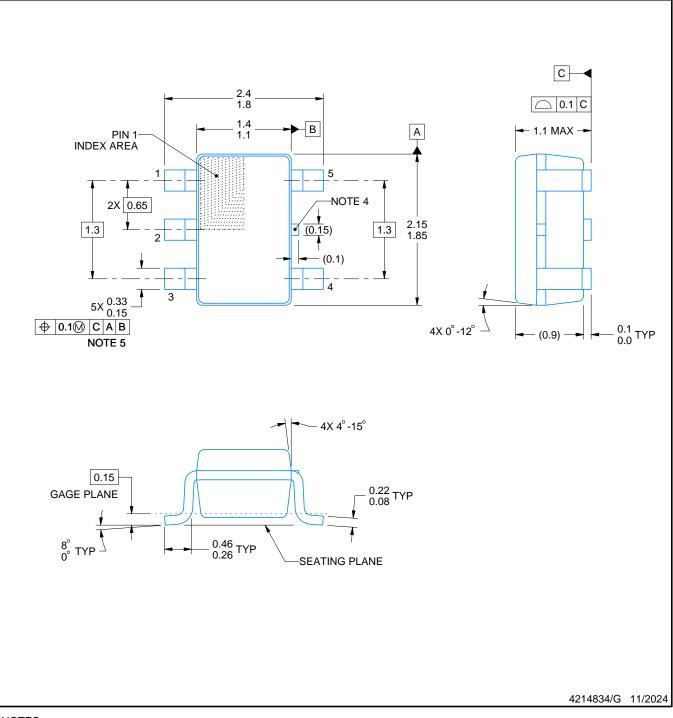
# **DCK0005A**



# **PACKAGE OUTLINE**

## SOT - 1.1 max height

SMALL OUTLINE TRANSISTOR



NOTES:

- 1. All linear dimensions are in millimeters. Any dimensions in parenthesis are for reference only. Dimensioning and tolerancing per ASME Y14.5M.
   This drawing is subject to change without notice.
   Reference JEDEC MO-203.

- 4. Support pin may differ or may not be present.5. Lead width does not comply with JEDEC.
- 6. Body dimensions do not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not exceed 0.25mm per side



## **DCK0005A**

# **EXAMPLE BOARD LAYOUT**

## SOT - 1.1 max height

SMALL OUTLINE TRANSISTOR



NOTES: (continued)

Publication IPC-7351 may have alternate designs.
 Solder mask tolerances between and around signal pads can vary based on board fabrication site.



## DCK0005A

# **EXAMPLE STENCIL DESIGN**

## SOT - 1.1 max height

SMALL OUTLINE TRANSISTOR



NOTES: (continued)

9. Laser cutting apertures with trapezoidal walls and rounded corners may offer better paste release. IPC-7525 may have alternate design recommendations.

10. Board assembly site may have different recommendations for stencil design.



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